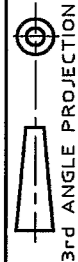


NUMBER 178295

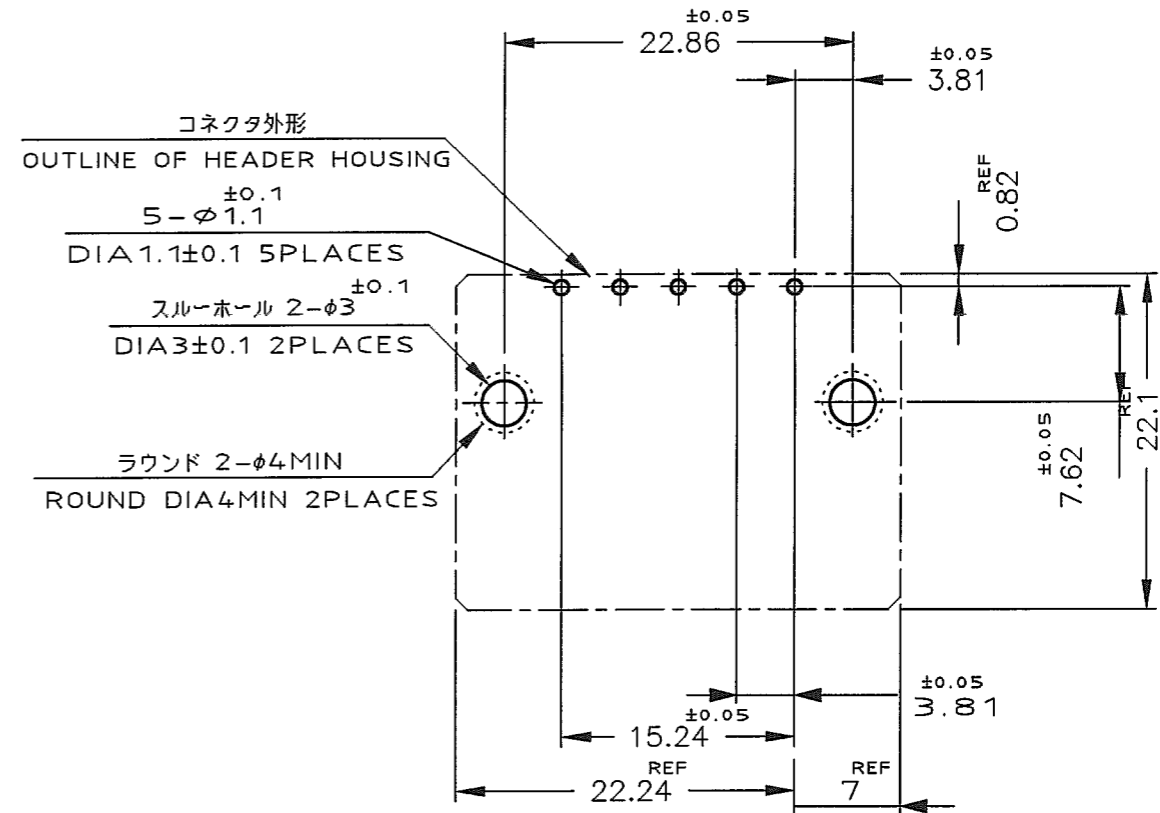
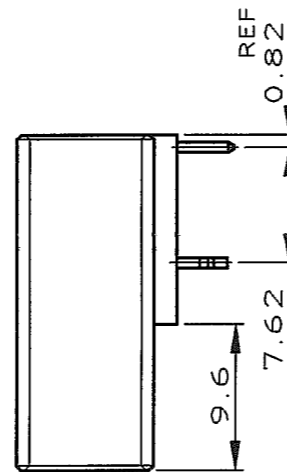
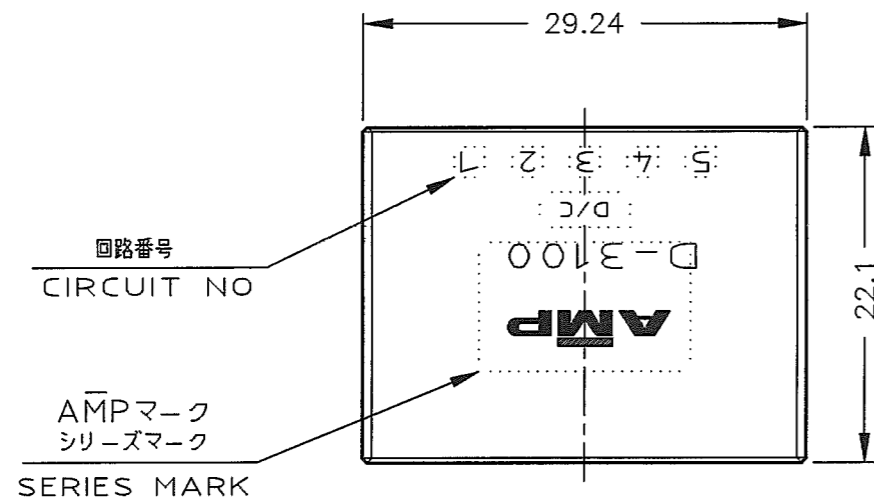


METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

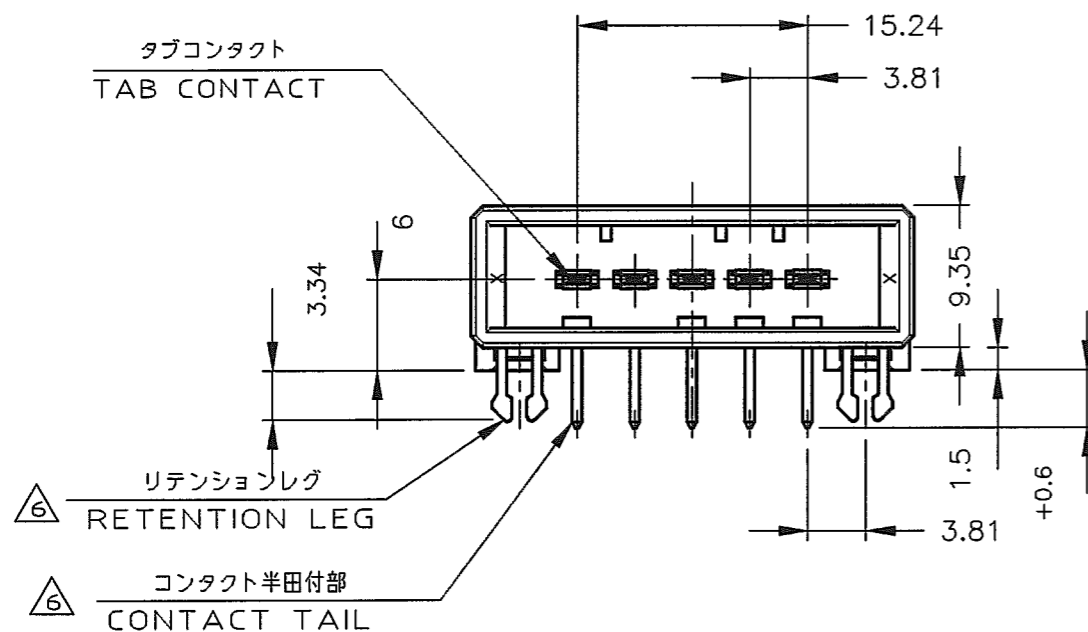
PRINT DIST

AMP-J REV.10/83



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
: ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき

△6	△4	1-178295-5
△6	△3	1-178295-3
△6	△2	1-178295-2
(FINISH)		製品番号 (PART NO.)

B	REVISED (FJD0-0039-03)	T S	S.M.	4/15/93
A	REVISED (FJD0-0097-03)	T S	S.M.	7-1/93
O	RELEASED (ECN J1184)	NM	H.O.	7-1/92
LTR	REVISION RECORD	DR	CHK	DATE

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WIRE RANGE mm (AWG)	INSULATION DIA mmφ
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照
DR. N. Matsubara 14 JUN 91	DE. N. Matsubara 14 JUN 91
CHK. T. Oobata 1 JUL '91	APP. S. MANABE 1 JUL '91

NAME 5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100		
一般公差 (GENERAL TOLERANCE)	SIZE	LOC
10mmF : ±0.3 10mmB 30mmF : ±0.4 30mmB 100mmF : ±0.5 角 度 : ±3'	A3	J
NUMBER	C-178295	
SCALE	REV.	SHEET
2-1	B	1 OF 1